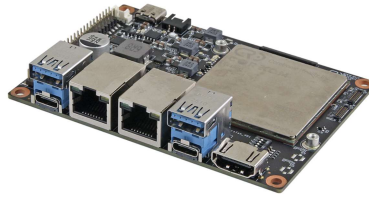


ACP-Q6490

PRELIMINARY



Product Features

- Qualcomm QCS6490 high level platform up to 2.7GHz
- Thin client concept and ruggedize, support a wide temperature range
- Strong Connectivity for WiFi, Ethernet, and BT
- AI Engine up to 12TOPS
- Various video interfaces and I/O connections: 2 USB3.2, HDMI, 4 COM, 40pin GPIO, 2 MIPI-CSI
- Ideal for embedded applications in fields like automotive markets, retail and box pc with AI solution

Specification

System Information

Processor QCS6490
Qualcomm® Kryo™ 670, 8 cores, up to 2.7 GHz, 12 TOPS (INT8)

System Memory 8GB LPDDR4

Software Support

OS Win 11 IoT Enterprise LTSC, Android 13, Ubuntu 20.04 LTS , Qualcomm Linux

Expansion

Expansion Optional M.2 M Key for NVMe or M.2 E Key for WIFI/BT (available for non-Wifi model)

Storage

UFS 128GB UFS

Display

Multiple Display HDMI or eDP 30pin (primary)
DP via Type-C(secondary)

Power Requirement

DC Input 1 x DC-In (20V@5A) or 1 x PD-in USB Type C (20V@5A) (BOM option)

External I/O

LAN Port 2 x 1Gb RJ45

USB 1 X USB Type-C
2 X USB 3.2 Gen 1 (Type-A)

I/O

UART 1 x Debug UART (Pin Header)

GPIO	1 X 40 Pin (QUP Configable (SPI / I2C / UART / I2S / I3C), PWM / DMIC)
RS232	4 x RS-232 (with RS-232 transceiver, via 2.0mm pitch WTB heater)
USB	2 X USB 2.0 (WTB Type, 2.0mm pitch)
Display	1 x eDP 30pins, 2 Lane
Audio	1 X Speaker Amplifier WSA 8835
WIFI	2 X Antenna IPEX Conn (Only available for Wi-Fi model)
Camera	2 X MIPI-CSI
RTC	Supported

Characteristics

Board Structure	2.5" SBC
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Mechanical & Environmental

Operating Temp.	-20°C ~ 65°C
Storage Temp.	-40°C ~ 80°C
Dimension (L x W)	100mm x 72mm x 23.7mm
Weight	150g